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(12) **United States Design Patent**
Ichitsubo et al.

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(54) **POWER AMPLIFIER MODULE**
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(73) Assignee: **Micro Mobio Corp.**, Palo Alto, CA (US)
(**) Term: **14 Years**

D368,261 S 3/1996 Shushurin
D380,737 S * 7/1997 Weir et al. D13/162
D400,512 S * 11/1998 Korhonen D13/184
D400,513 S * 11/1998 Seirio D13/184
D402,275 S * 12/1998 Korhonen D13/184
D404,396 S 1/1999 Mackie
D446,499 S 8/2001 Andre
D451,479 S * 12/2001 Bateson et al. D13/152
D451,482 S * 12/2001 Vanderheiden et al. D13/162
2004/0090266 A1 * 5/2004 Sakai et al. 330/129

* cited by examiner

(21) Appl. No.: **29/185,022**
(22) Filed: **Jun. 20, 2003**

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Related U.S. Application Data

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(51) **LOC (7) Cl.** **13-03**
(52) **U.S. Cl.** **D13/184; D14/240; D13/110**
(58) **Field of Search** D14/240, 349, D14/353, 242, 243, 248, 256, 299, 358, 433, 357, 188; 455/151.1–151.4, 550–575, 569.1, 569.2; D13/184, 147, 110, 168; 379/433.01–13, 434, 419, 418

(57) **CLAIM**

The ornamental design for the power amplifier module, as shown and described.

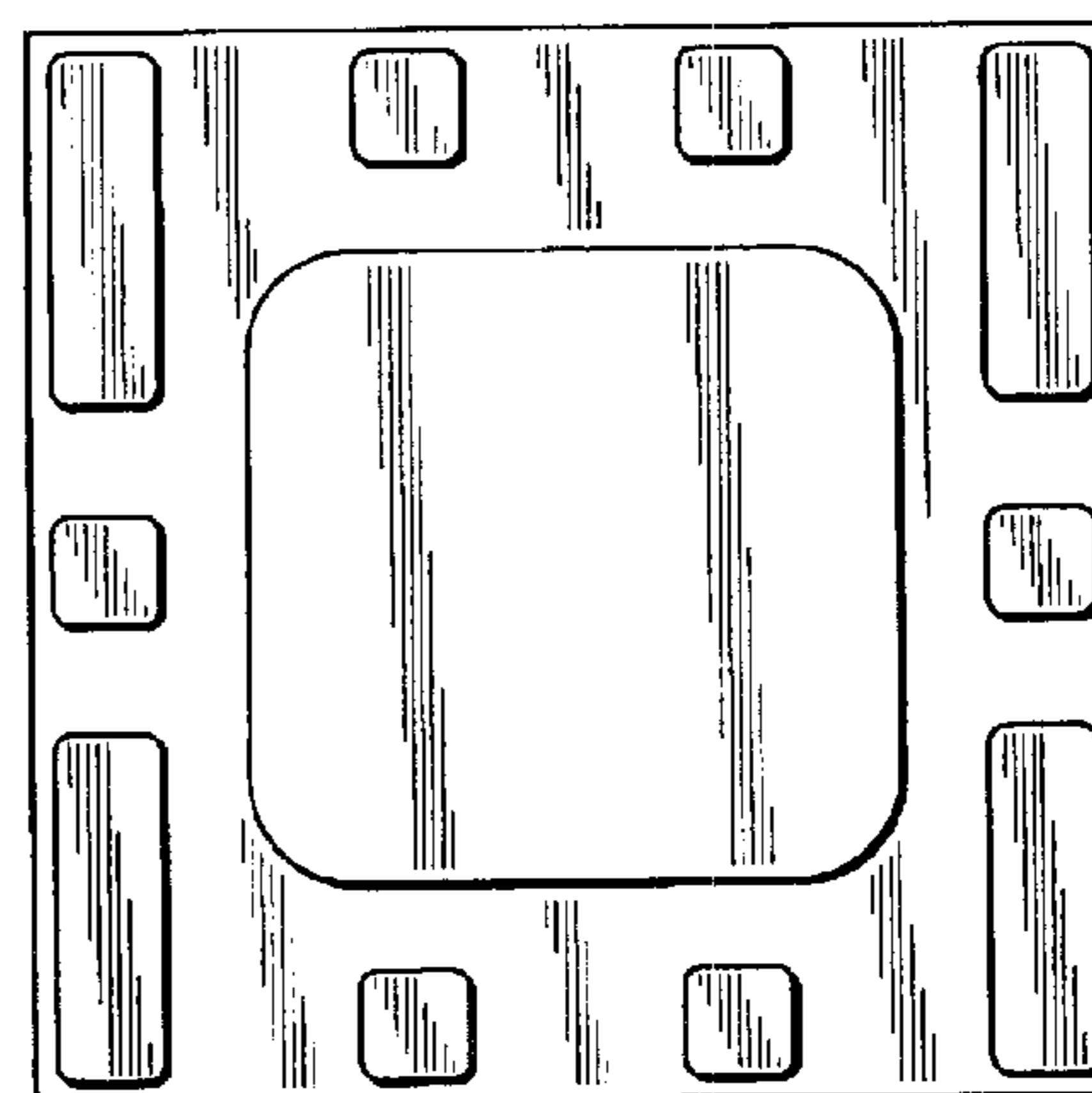
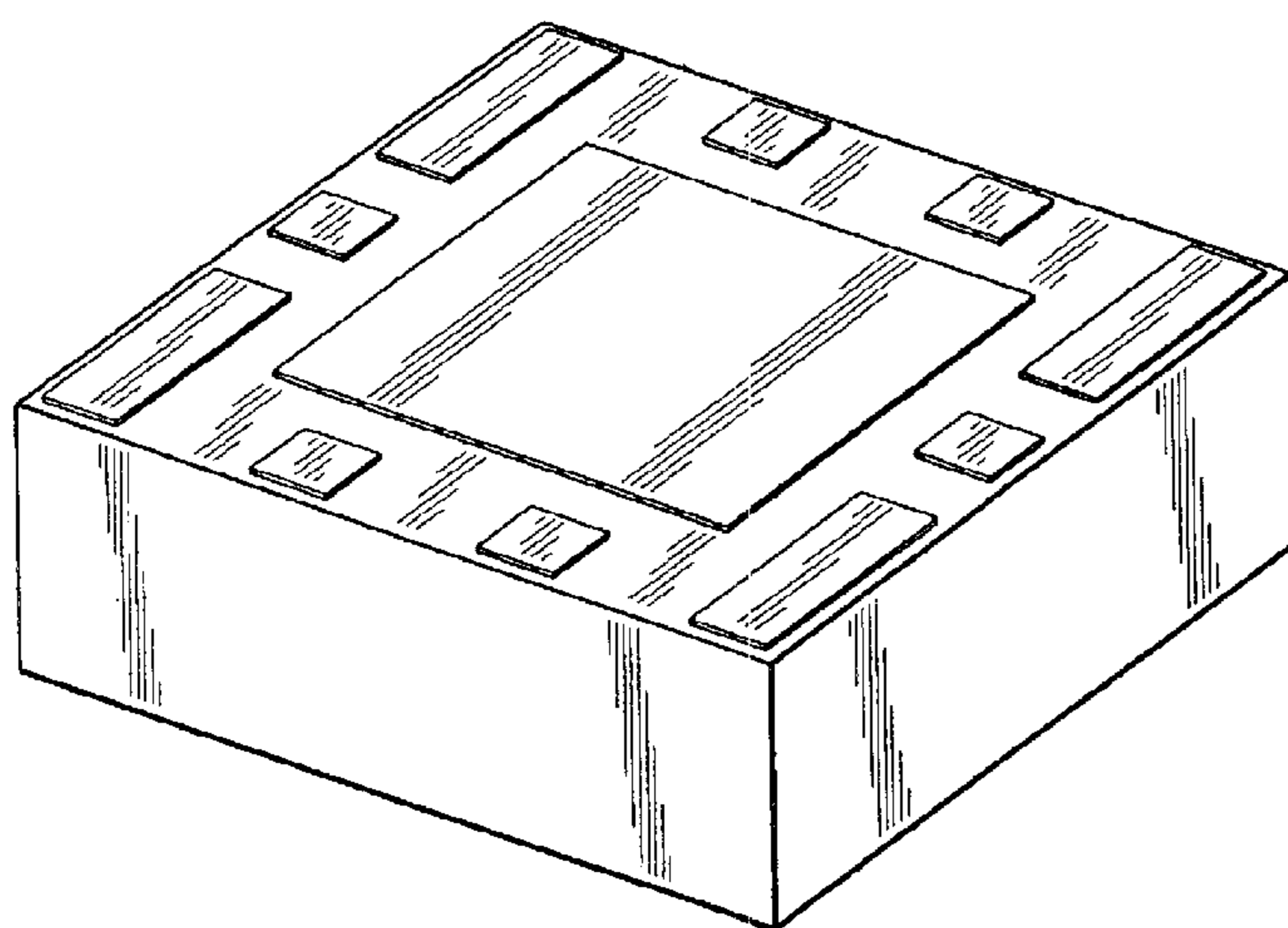
DESCRIPTION

FIG. 1 is a top perspective view of a power amplifier module showing our new design;
FIG. 2 is a bottom perspective view thereof;
FIG. 3 is a bottom plan view thereof; and,
FIG. 4 is a bottom plan view of a modified embodiment of the design shown in FIGS. 1 through 3.

(56) **References Cited**
U.S. PATENT DOCUMENTS

D289,747 S 5/1987 Sethares

1 Claim, 2 Drawing Sheets



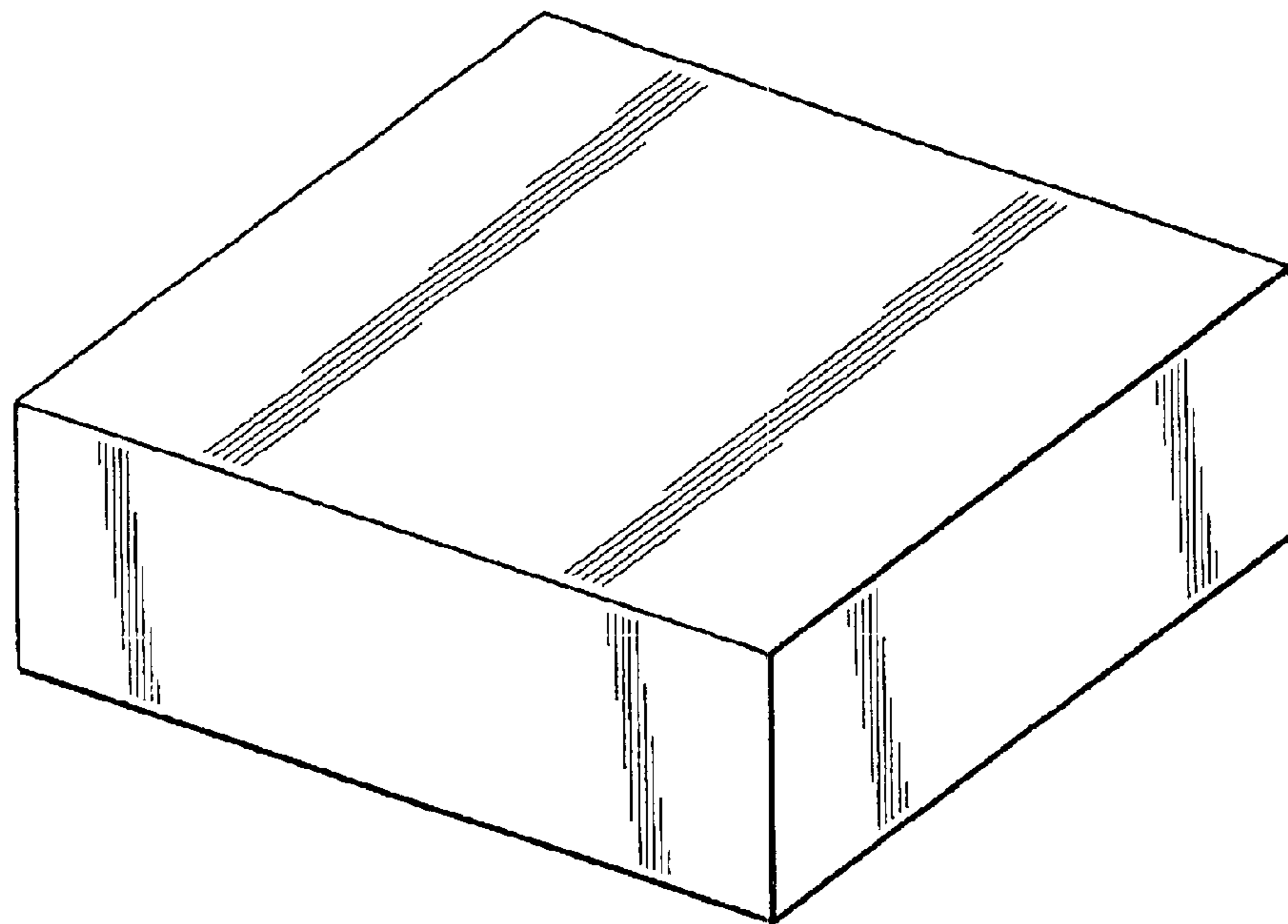


FIG. 1

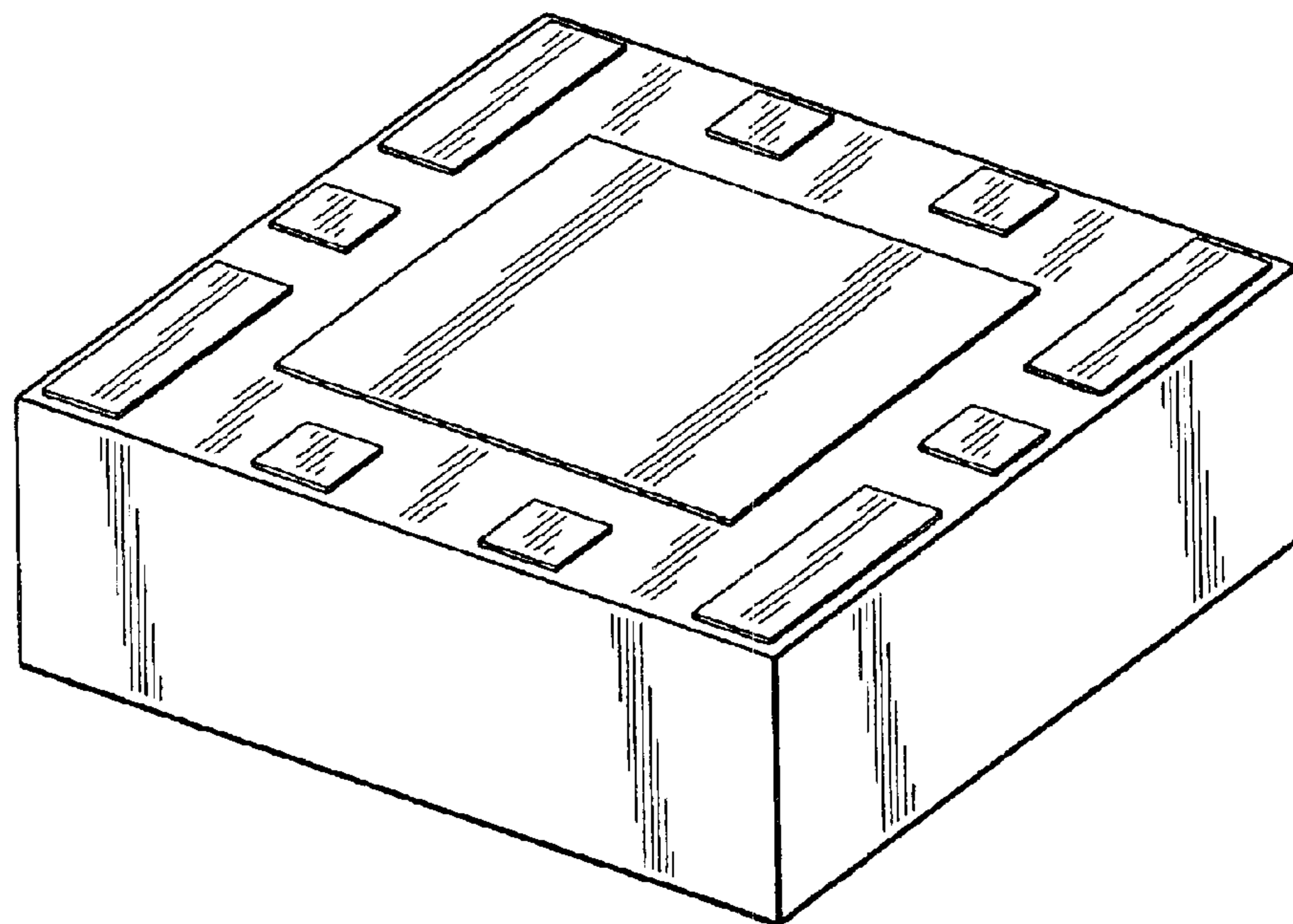


FIG. 2

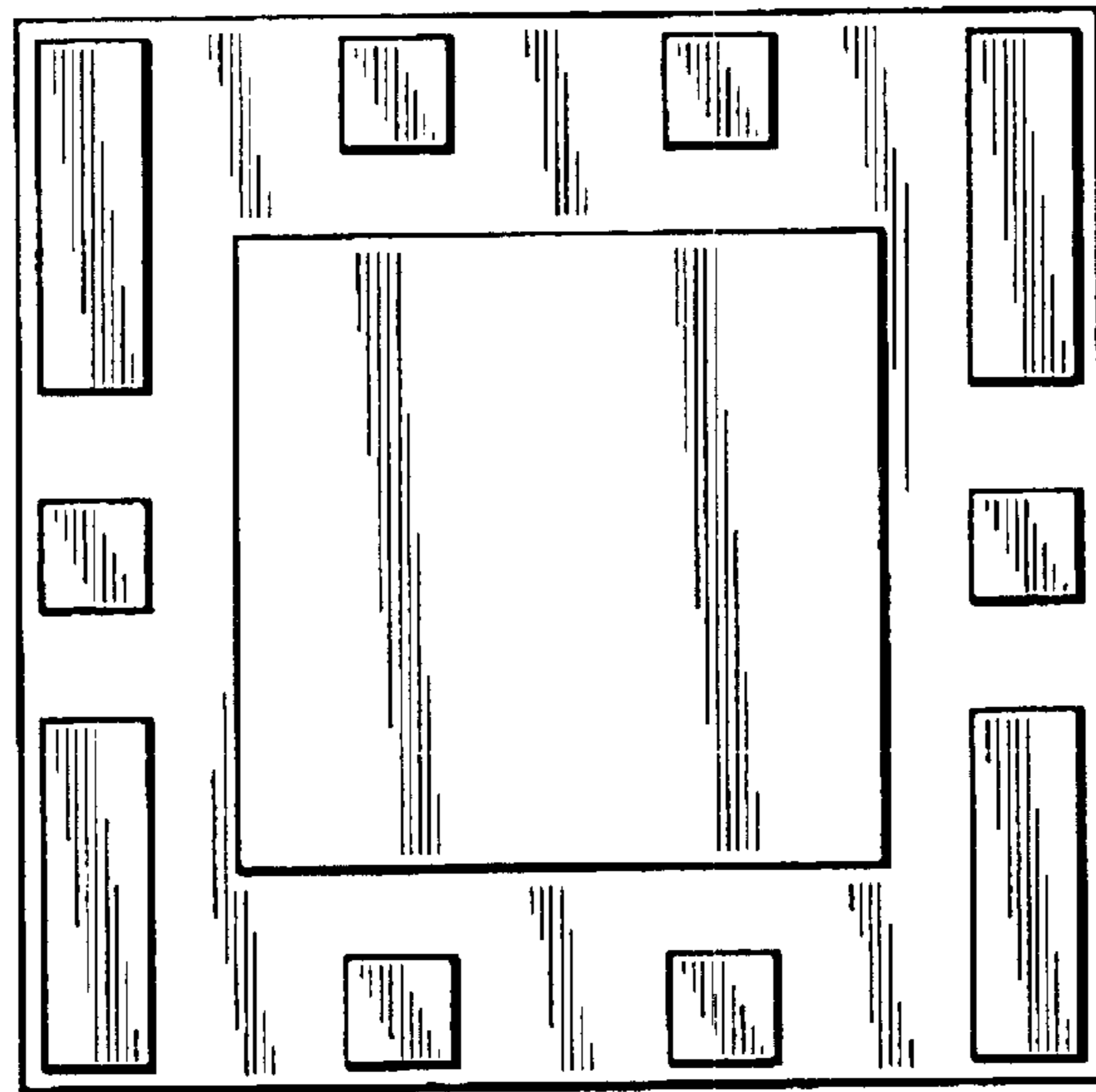


FIG. 3

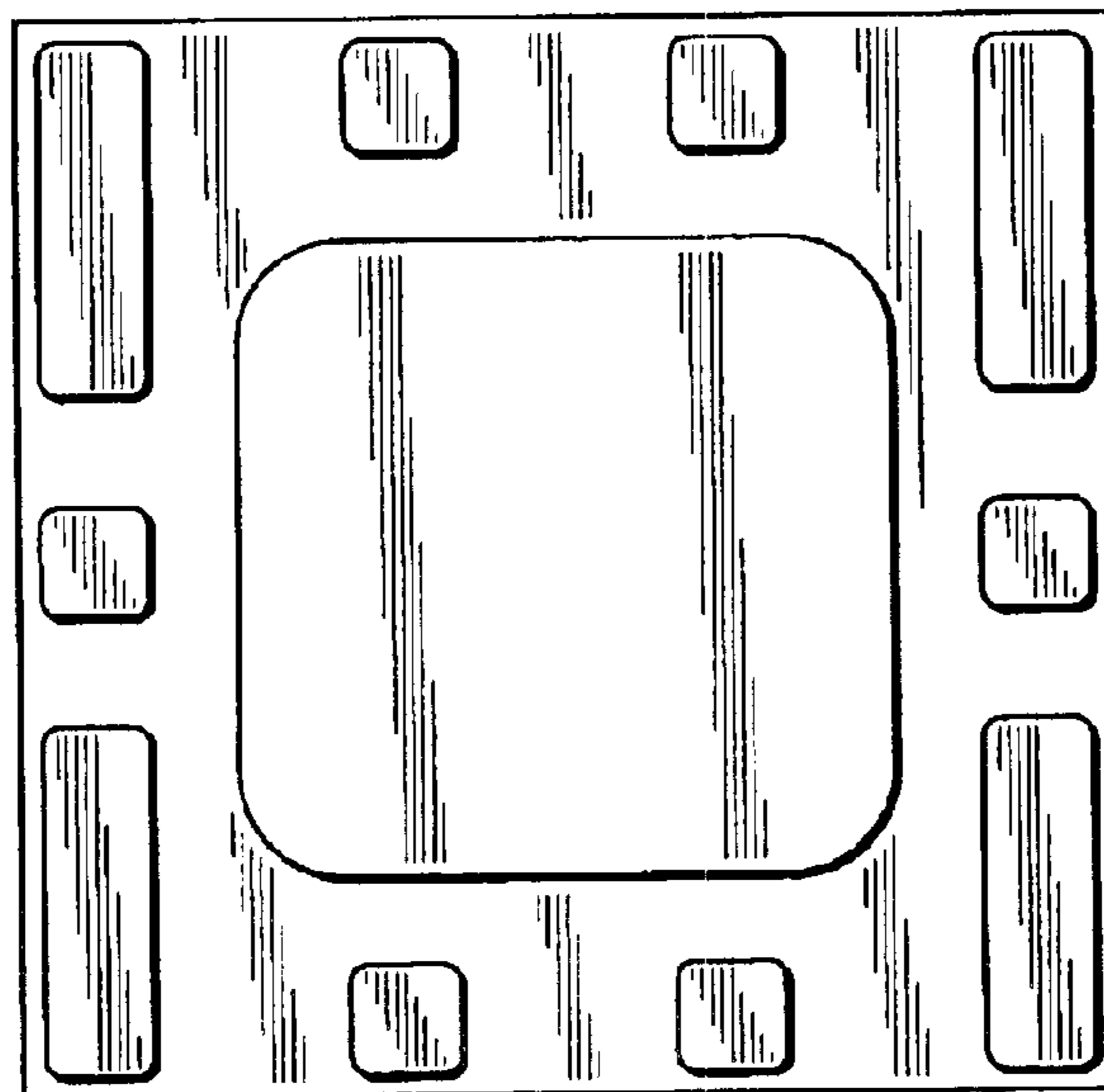


FIG. 4